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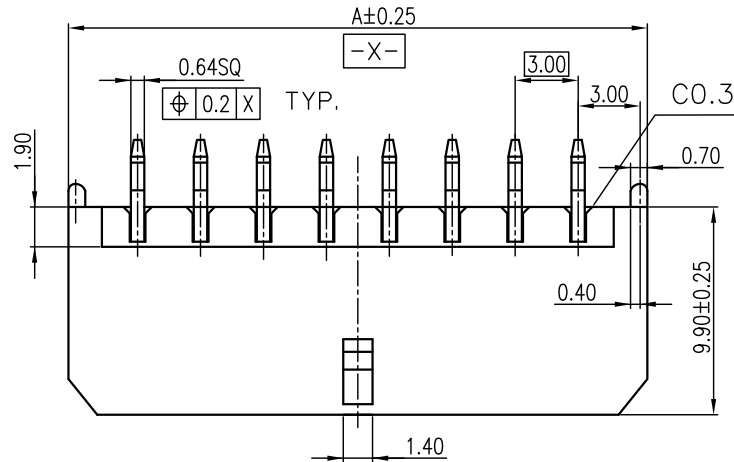
The marking on this product doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.



ORIGINAL



REVISIONS			
SYM	ECN No.	DESCRIPTION	DATE
A		RELEASE FOR RoHS	07/04/2006
B	NE-06295	MODIFIED DRAWING	09/06/2006
C	NE-09209	MODIFIED DRAWING	12/30/2009
D	NE-10003	MODIFIED DRAWING	01/07/2010
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010
F	NE-11043	MODIFIED DRAWING	03/28/2010
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011
C1	NE-12012	ADDED POST DIM. 0.95	01/31/2012
D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012
E1	NE-12113	REMOVE 2 POS OPTIONS AND UPDATE PACKING QUANTITY.	07/04/2012
F1	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013
A2	NE-13197	ADDED DIM & UPDATE FINISH NOTE	12/06/2013
B2	NE-15054	ADD 2PIN AND UPDATE PACKING	04/29/2015

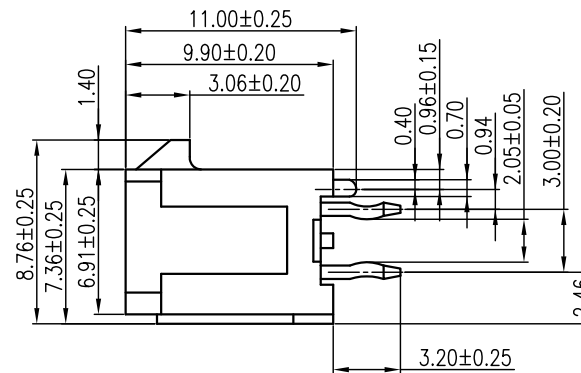
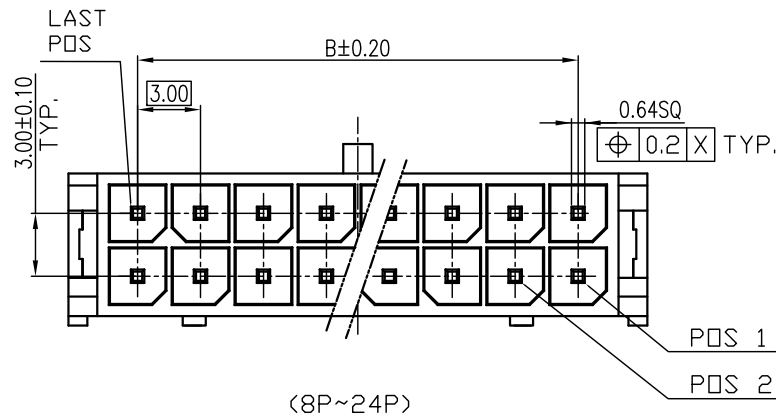


PART NO. G881AXX1X2TEU
No. OF CIRCUIT

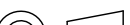
CONTACT FINISH
0: Tin (OVERALL)
1: FLASH GOLD (OVERALL)
2: 15 u" GOLD
3: 30 u" GOLD

NOTE:

- 1.INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
- 2.CONTACT MATERIAL:COPPER ALLOY;
- 3.FINISH:
CONTACT: SELECTIVE PLATING. ;
SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN.OVERALL.
- 4.THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC FOR RoHS.
- 5.PACKING MUST BE PER Amphenol PACKING SPECIFICATION



24	39.60	33.00
22	36.60	30.00
20	33.60	27.00
18	30.60	24.00
16	27.60	21.00
14	24.60	18.00
12	21.60	15.00
10	18.60	12.00
08	15.60	9.00
06	12.60	6.00
04	9.60	3.00
02	6.60	
NO. OF CIRCUIT	A	B

TOLERANCE		APPROVALS		DATE	TITLE			CIRCUIT				
X.		DRAWN	Aqua Chou	04/29/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT			Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation				
X.X ±0.30			CHECKED	Roger Tsai							04/29/2015	
X.XX ±0.20				APPROVED							Roger Tsai	04/29/2015
X.XXX ±0.10												
ANGULAR ±1°			Roger Tsai	04/29/2015		UNIT mm	SIZE A3	PART No. G881AXX1X2TEU				
UNLESS OTHERWISE SPECIFIED		DWG TYPE CUST DWG	PROJECT CODE PHD			SCALE NA	SHEET 1 OF 3	DWG No. G881AXX1X2TEU		REV. B2		

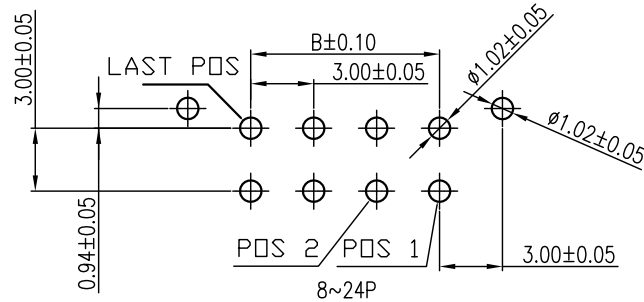
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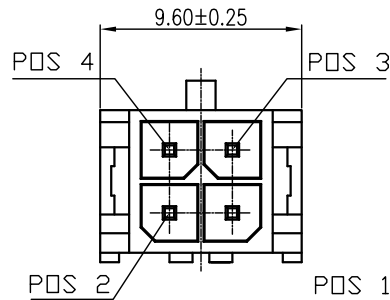
ORIGINAL



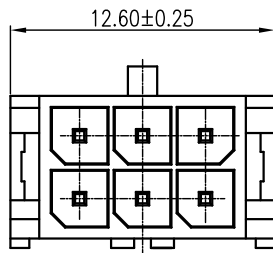
REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	07/04/2006	Armstrong Kao
B	NE-06295	MODIFIED DRAWING	09/06/2006	Edward Wu
C	NE-09209	MODIFIED DRAWING	12/30/2009	Arron Lin
D	NE-10003	MODIFIED DRAWING	01/07/2010	Arron Lin
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010	Roger Tsai
F	NE-11043	MODIFIED DRAWING	03/28/2010	Arron Lin
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011	Arron Lin
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011	Arron Lin
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D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012	Arron Lin
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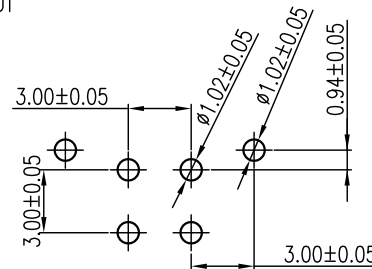
RECOMMENDED PCB LAYOUT
(THICKNESS: 1.60mm)



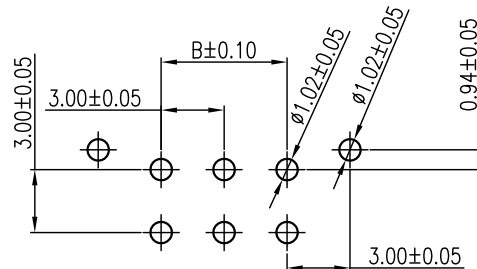
(2X2POS)



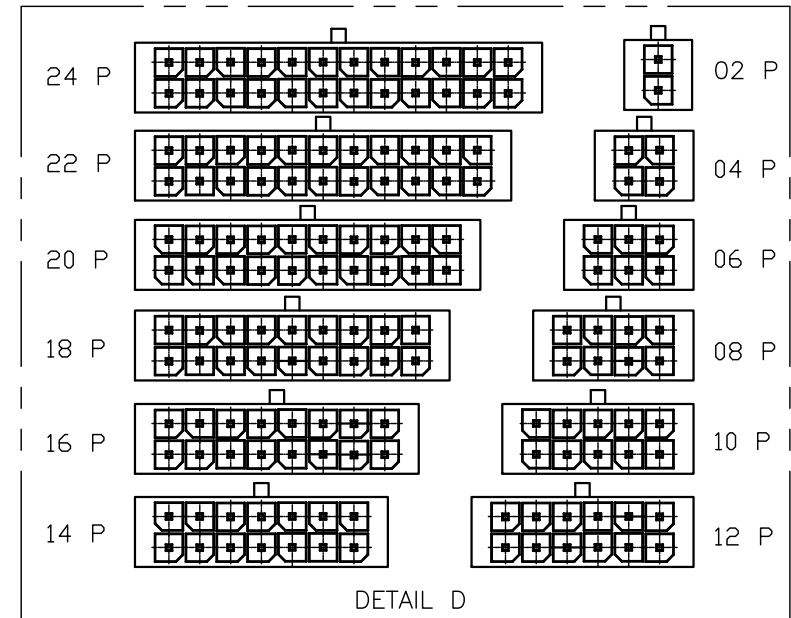
(2X3POS)

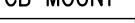


RECOMMENDED PCB LAYOUT
(THICKNESS: 1.60mm)



RECOMMENDED PCB LAYOUT
(THICKNESS: 1.60mm)



TOLERANCE		APPROVALS		DATE	TITLE				Amphenol [®]			
X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10		DRAWN Aqua Chou		04/29/2015	G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT				Amphenol Corporation			
		CHECKED Roger Tsai		04/29/2015					Amphenol Taiwan Corporation			
		APPROVED Roger Tsai		04/29/2015								
ANGULAR ±1°						UNIT mm	SIZE A3	PART No.	G881AXX1X2TEU			
UNLESS OTHERWISE SPECIFIED		CUST DWG		PROJECT CODE PHD		SCALE NA	SHEET 2 OF 3	DWG No.	G881AXX1X2TEU			REV. B2

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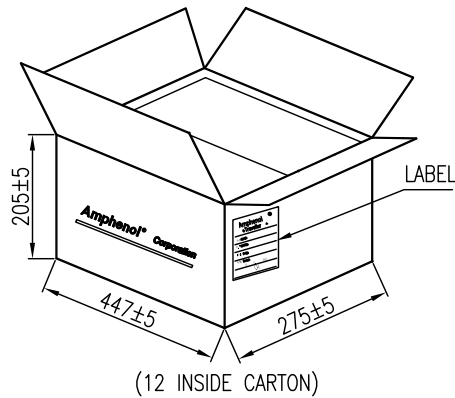
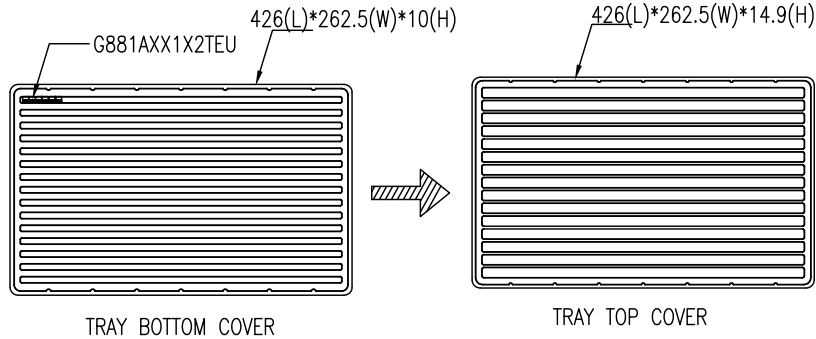
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POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

- NOTE:
1. MATERIAL : TRANSPARENT CONDUCTIVE POLYSTYRENE ALLOY
 2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
 3. THICKNESS : 0.80±0.05mm.

TOLERANCE		APPROVALS		DATE	TITLE G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT		Amphenol [®] Amphenol Corporation Amphenol Taiwan Corporation		
X.		DRAWN	Aqua Chou	04/29/2015					
X.X	±0.30	CHECKED	Roger Tsai	04/29/2015			PART No. G881AXX1X2TEU		
X.XX	±0.20	APPROVED	Roger Tsai	04/29/2015			DWG No. G881AXX1X2TEU		
X.XXX	±0.10	DWG TYPE	CUST DWG	PROJECT CODE	PHD	UNIT	mm	SIZE	A3
ANGULAR	±1°					SCALE	NA	SHEET	3 OF 3
UNLESS OTHERWISE SPECIFIED								REV.	B2